



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC019N06NS	Issued	12. August 2021
MA#	MA005620253		
Package	PG-TDSON-8-17	Weight*	119.40 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.188	0.99	0.99	9948	9948
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		317	
	non noble metal	copper	7440-50-8	37.762	31.63	31.67	316264	316676
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	375	375
encapsulation	organic material	carbon black	1333-86-4	0.131	0.11		1101	
	plastics	epoxy resin	-	5.127	4.29		42941	
	inorganic material	silicondioxide	60676-86-0	38.563	32.30	36.70	322977	367019
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12158	12158
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1386	1386
solder	non noble metal	tin	7440-31-5	0.034	0.03		281	
	noble metal	silver	7440-22-4	0.042	0.04		351	
	non noble metal	lead	7439-92-1	1.602	1.34	1.41	13421	14053
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	zinc	7440-66-6	0.026	0.02		222	
	non noble metal	iron	7439-89-6	0.529	0.44		4431	
	non noble metal	copper	7440-50-8	21.482	17.99	18.46	179920	184628
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.013	0.01		113	
	non noble metal	iron	7439-89-6	0.269	0.22		2250	
	non noble metal	copper	7440-50-8	10.909	9.14	9.37	91366	93757
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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